

2016 21st IEEE European Test Symposium (ETS 2016)

**Amsterdam, Netherlands
23 – 27 May 2016**



IEEE Catalog Number: CFP16216-POD
ISBN: 978-1-4673-9660-8

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IEEE Catalog Number:	CFP16216-POD
ISBN (Print-On-Demand):	978-1-4673-9660-8
ISBN (Online):	978-1-4673-9659-2
ISSN:	1530-1877

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